

## Flash Microcontroller Programming Specification

### 1.0 DEVICE OVERVIEW

This document includes the programming specifications for the following devices:

PIC18F6585PIC18F6680PIC18F8585PIC18F8680

#### 2.0 PROGRAMMING OVERVIEW

PIC18FXX80/XX85 devices can be programmed using either the high-voltage In-Circuit Serial Programming<sup>TM</sup> (ICSP<sup>TM</sup>) method, or the low-voltage ICSP method. Both of these programming methods can be done with the device in the user's system. The low-voltage ICSP method is slightly different than the high-voltage method, and these differences are noted where applicable. This programming specification applies to PIC18FXX80/XX85 devices in all package types.

### 2.1 Hardware Requirements

## 2.1.1 HIGH-VOLTAGE ICSP PROGRAMMING

In High-Voltage ICSP mode, these devices require two programmable power supplies: one for VDD and one for MCLR/VPP. Both supplies should have a minimum resolution of 0.25V. Refer to Section 6.0 "AC/DC Characteristics Timing Requirements for Program/ Verify Test Mode" for additional hardware parameters.

## 2.1.2 LOW-VOLTAGE ICSP PROGRAMMING

In Low-Voltage ICSP mode, these devices can be programmed using a VDD source in the operating range. This only means that MCLR/VPP does not have to be brought to a different voltage but can instead be left at the normal operating voltage. Refer to Section 6.0 "AC/DC Characteristics Timing Requirements for Program/ Verify Test Mode" for additional hardware parameters.

### 2.2 Pin Diagrams

The pin diagrams for the PIC18FXX80/XX85 family are shown in Figure 2-1, Figure 2-2 and Figure 2-3. The pin descriptions of these diagrams do not represent the complete functionality of the device types. Users should refer to the appropriate device data sheet for complete pin descriptions.

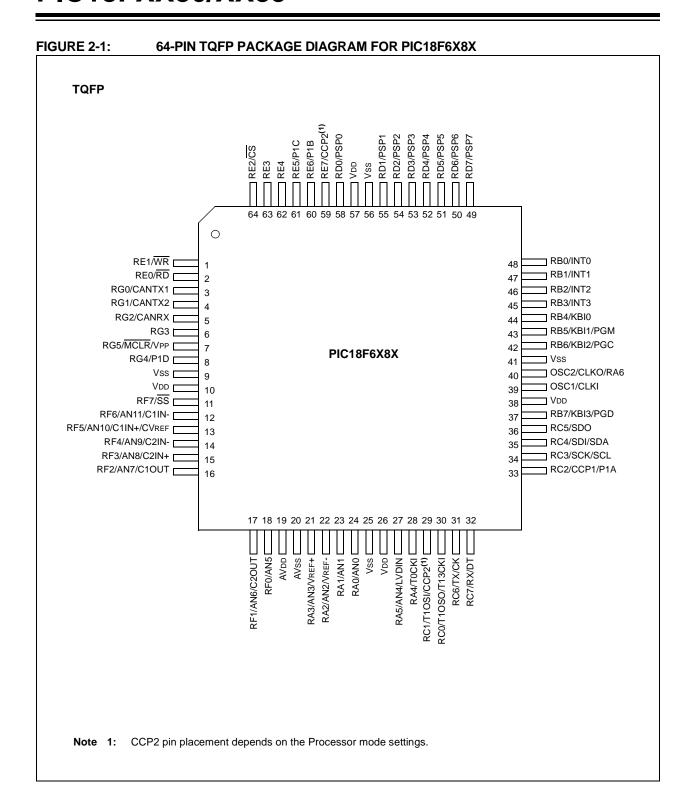
TABLE 2-1: PIN DESCRIPTIONS (DURING PROGRAMMING): PIC18FXX80/XX85

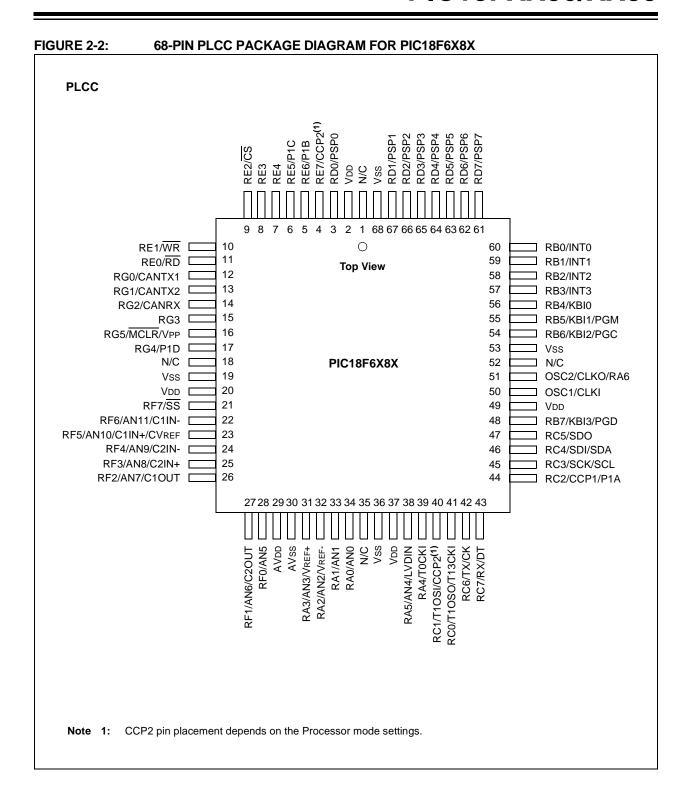
Pin Name	During Programming		
Pin Name	Pin Name	Pin Type	Pin Description
MCLR/Vpp/RA5	VPP	Р	Programming Enable
VDD <sup>(2)</sup>	Vdd	Р	Power Supply
VSS <sup>(2)</sup>	Vss	Р	Ground
AVDD <sup>(2)</sup>	AVDD	Р	Analog Power Supply
AVSS <sup>(2)</sup>	AVss	Р	Analog Ground
RB5	PGM	I	Low-Voltage ICSP™ Input when LVP Configuration bit equals '1' (1)
RB6	PGC	I	Serial Clock
RB7	PGD	I/O	Serial Data
OSC1	OSC1	I	Oscillator Input (needs to be pulled high during programming.)

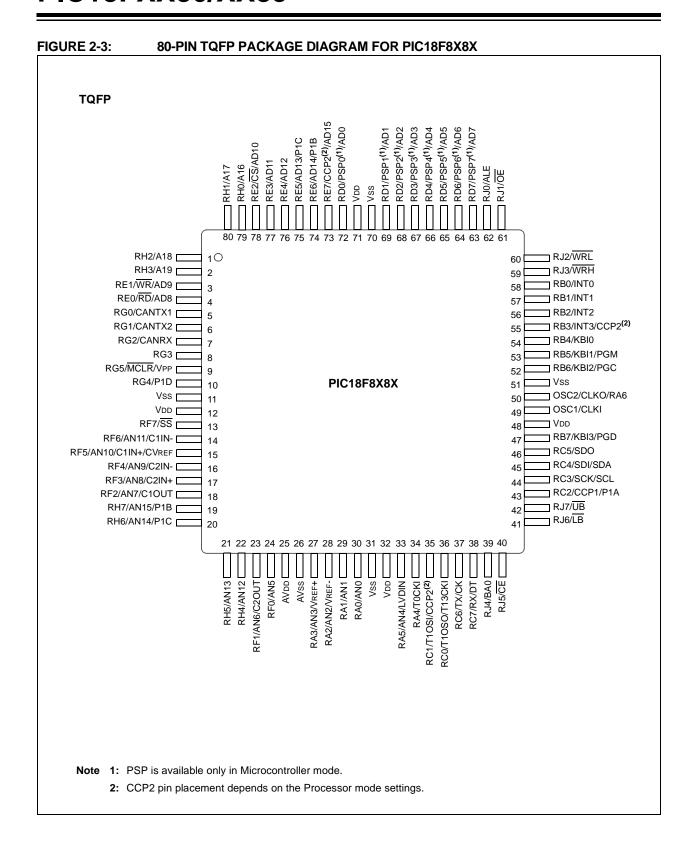
**Legend:** I = Input, O = Output, P = Power

Note 1: See Section 5.3 "Low-Voltage Programming (LVP) Bit" for more detail.

2: All power supplies and ground must be connected.







### 2.3 Memory Map

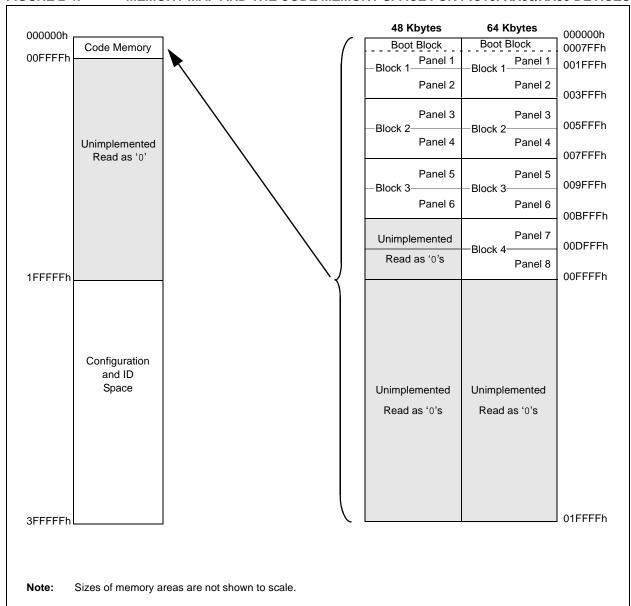
The code memory space extends from 0000h to 0FFFFh (64 Kbytes) in four 16-Kbyte blocks. However, addresses 0000h through 07FFh define a "Boot Block" region that is treated separately from Block 1. All of these blocks define code protection boundaries within the code memory space.

In contrast, code memory panels are defined in 8-Kbyte boundaries. Panels are discussed in greater detail in **Section 3.2 "Code Memory Programming"**.

TABLE 2-2: IMPLEMENTATION OF CODE MEMORY

Device	Code Memory Size (Bytes)
PIC18F6585	0000h - 00BFFFh (48K)
PIC18F8585	000011 - 00DFFF11 (40K)
PIC18F6680	0000h -00FFFFh (64K)
PIC18F8680	

FIGURE 2-4: MEMORY MAP AND THE CODE MEMORY SPACE FOR PIC18FXX80/XX85 DEVICES



In addition to the code memory space, there are three blocks in the configuration and ID space that are accessible to the user through table reads and table writes. Their locations in the memory map are shown in Figure 2-5.

Users may store identification information (ID) in eight ID registers. These ID registers are mapped in addresses 200000h through 200007h. The ID locations read out normally even after code protection is applied.

Locations, 300000h through 30000Dh, are reserved for the Configuration bits. These bits select various device options and are described in **Section 5.0 "Configuration Word"**. These Configuration bits read out normally even after code protection.

Locations, 3FFFFEh and 3FFFFh, are reserved for the device ID bits. These bits may be used by the programmer to identify what device type is being programmed and are described in **Section 5.0** "**Configuration Word**". These device ID bits read out normally even after code protection.

#### 2.3.1 MEMORY ADDRESS POINTER

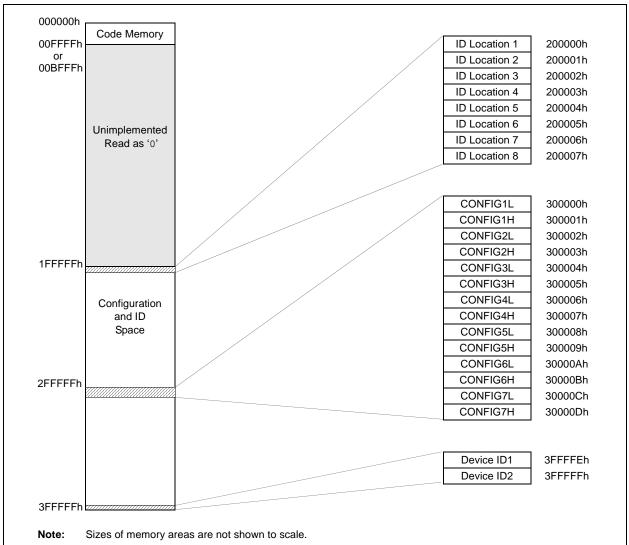
Memory in the address space, 000000h to 3FFFFh, is addressed via the Table Pointer which is comprised of three pointer registers:

- TBLPTRU, at RAM address 0FF8h
- · TBLPTRH, at RAM address 0FF7h
- · TBLPTRL, at RAM address 0FF6h

TBLPTRU	TBLPTRH	TBLPTRL
Addr[21:16]	Addr[15:8]	Addr[7:0]

The 4-bit command, '0000' (core Instruction), is used to load the Table Pointer prior to using many read or write operations.

FIGURE 2-5: CONFIGURATION AND ID LOCATIONS FOR PIC18FXX80/XX85 DEVICES



# 2.4 High-Level Overview of the Programming Process

Figure 2-7 shows the high-level overview of the programming process. First, a Bulk Erase is performed. Next, the code memory, ID locations and data EEPROM are programmed. These memories are then verified to ensure that programming was successful. If no errors are detected, the Configuration bits are then programmed and verified.

## 2.5 Entering High-Voltage ICSP Program/Verify Mode

The High-Voltage ICSP Program/Verify mode is entered by holding PGC and PGD low and then raising MCLR/VPP to VIHH (high voltage). Once in this mode, the code memory, data EEPROM, ID locations and Configuration bits can be accessed and programmed in serial fashion.

The sequence that enters the device into the Program/ Verify mode places all unused I/Os in the high-impedance state.

## 2.5.1 ENTERING LOW-VOLTAGE ICSP PROGRAM/VERIFY MODE

When the LVP Configuration bit is '1' (see Section 5.3 "Low-Voltage Programming (LVP) Bit"), the Low-Voltage ICSP mode is enabled. Low-Voltage ICSP Program/Verify mode is entered by holding PGC and PGD low, placing a logic high on PGM and then raising MCLR/VPP to VIH. In this mode, the RB5/PGM pin is dedicated to the programming function and ceases to be a general purpose I/O pin.

The sequence that enters the device into the Program/ Verify mode places all unused I/Os in the high-impedance state.

FIGURE 2-6: ENTERING HIGH-VOLTAGE PROGRAM/VERIFY MODE

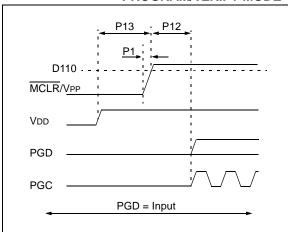


FIGURE 2-7: HIGH-LEVEL PROGRAMMING FLOW

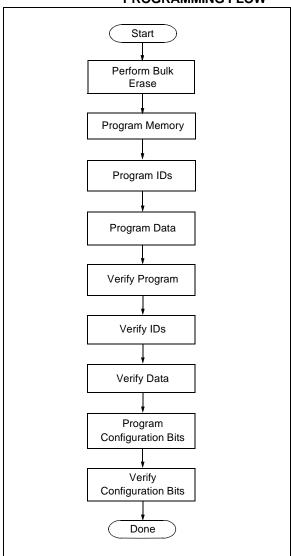
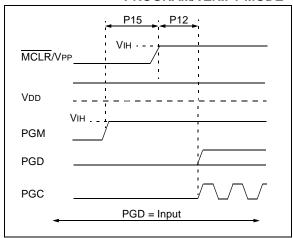


FIGURE 2-8: ENTERING LOW-VOLTAGE PROGRAM/VERIFY MODE



### 2.6 Serial Program/Verify Operation

The PGC pin is used as a clock input pin and the PGD pin is used for entering command bits and data input/output during serial operation. Commands and data are transmitted on the rising edge of PGC, latched on the falling edge of PGC and are Least Significant bit (LSb) first.

#### 2.6.1 4-BIT COMMANDS

All instructions are 20 bits, consisting of a leading 4-bit command followed by a 16-bit operand, which depends on the type of command being executed. To input a command, PGC is cycled four times. The commands needed for programming and verification are shown in Table 2-3.

Depending on the 4-bit command, the 16-bit operand represents 16 bits of input data or 8 bits of input data and 8 bits of output data.

Throughout this specification, commands and data are presented as illustrated in Table 2-4. The 4-bit command is shown Most Significant bit (MSb) first. The command operand, or "Data Payload", is shown <MSB><LSB>. Figure 2-9 demonstrates how to serially present a 20-bit command/operand to the device.

#### 2.6.2 CORE INSTRUCTION

The core instruction passes a 16-bit instruction to the CPU core for execution. This is needed to set up registers as appropriate for use with other commands.

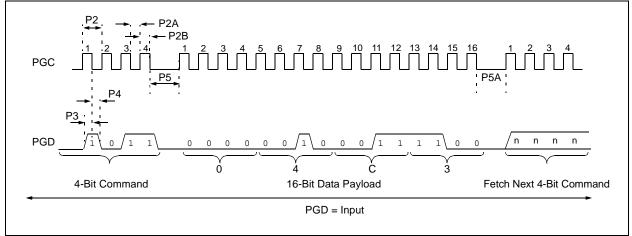
TABLE 2-3: COMMANDS FOR PROGRAMMING

Description	4-Bit Command
Core Instruction (shift in16-bit instruction)	0000
Shift out TABLAT register	0010
Table Read	1000
Table Read, Post-Increment	1001
Table Read, Post-Decrement	1010
Table Read, Pre-Increment	1011
Table Write	1100
Table Write, Post-Increment by 2	1101
Table Write, Post-Decrement by 2	1110
Table Write, Start Programming	1111

TABLE 2-4: SAMPLE COMMAND SEQUENCE

4-Bit Command	Data Payload	Core Instruction
1101	3C 40	Table Write, post-increment by 2





### 3.0 DEVICE PROGRAMMING

### 3.1 High-Voltage ICSP Bulk Erase

Erasing code or data EEPROM is accomplished by writing an "Erase Option" to address 3C0004h. Code memory may be erased portions at a time, or the user may erase the entire device in one action. "Bulk Erase" operations will also clear any code-protect settings associated with the memory block erased. Erase options are detailed in Table 3-1.

TABLE 3-1: BULK ERASE OPTIONS

Description	Data
Chip Erase	80h
Erase Data EEPROM	81h
Erase Boot Block	83h
Erase Block 1	88h
Erase Block 2	89h
Erase Block 3	8Ah
Erase Block 4	8Bh

The actual Bulk Erase function is a self-timed operation. Once the erase has started (falling edge of the 4th PGC after the "Write" command), serial execution will cease until the erase completes (parameter P11). During this time, PGC may continue to toggle but PGD must be held low.

The code sequence to erase the entire device is shown in Table 3-2 and the flowchart is shown in Figure 3-1.

Note: A Bulk Erase is the only way to reprogram code-protect bits from an ON state to an OFF state.

Non code-protect bits are not returned to default settings by a Bulk Erase. These bits should be programmed to '1's, as outlined in **Section 3.6 "Configuration Bits Programming"**.

TABLE 3-2: BULK ERASE COMMAND SEQUENCE

4-Bit Command	Data Payload	Core Instruction
0000	8E A6	BSF EECON1, EEPGD
0000	8C A6	BSF EECON1, CFGS
0000	0E 3C	MOVLW 3Ch
0000	6E F8	MOVWF TBLPTRU
0000	0E 00	MOVLW 00h
0000	6E F7	MOVWF TBLPTRH
0000	0E 04	MOVLW 04h
0000	6E F6	MOVWF TBLPTRL
1100	00 80	Write 80h TO 3C0004h to
		erase entire device.
0000	00 00	NOP
0000	00 00	Hold PGD low until
		erase completes.

FIGURE 3-1: BULK ERASE FLOW

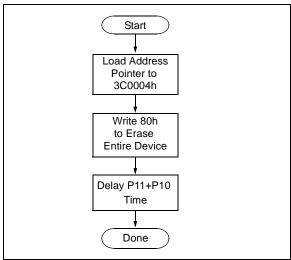
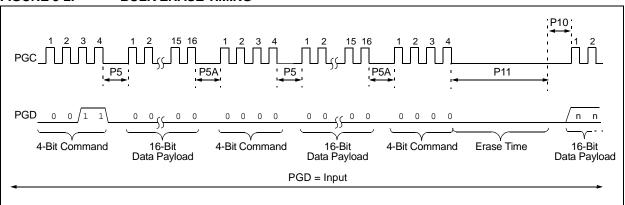


FIGURE 3-2: BULK ERASE TIMING



#### 3.1.1 LOW-VOLTAGE ICSP BULK ERASE

When using low-voltage ICSP, the part must be supplied by the voltage specified in parameter D111 if a Bulk Erase is to be executed. All other Bulk Erase details as described above apply.

If it is determined that a program memory erase must be performed at a supply voltage below the Bulk Erase limit, refer to the erase methodology described in Section 3.1.2 "ICSP Multi-Panel Single Row Erase" and Section 3.2.2 "Modifying Code Memory".

If it is determined that a data EEPROM erase must be performed at a supply voltage below the Bulk Erase limit, follow the methodology described in **Section 3.3** "Data EEPROM Programming" and write '1's to the array.

## 3.1.2 ICSP MULTI-PANEL SINGLE ROW ERASE

Irrespective of whether high or low-voltage ICSP is used, it is possible to erase single row (64 bytes of data) in all panels at once. For example, in the case of a 64-Kbyte device (8 panels), 512 bytes through 64 bytes in each panel can be erased simultaneously during each erase sequence. In this case, the offset of the

erase within each panel is the same (see Figure 3-5). Multi-panel single row erase is enabled by appropriately configuring the Programming Control register located at 3C0006h.

The multi-panel single row erase duration is externally timed and is controlled by PGC. After a "Start Programming" command is issued (4-bit, '1111'), a NOP is issued, where the 4th PGC is held high for the duration of the programming time, P9.

After PGC is brought low, the programming sequence is terminated. PGC must be held low for the time specified by parameter P10 to allow high-voltage discharge of the memory array.

The code sequence to program a PIC18FXX80/XX85 device is shown in Table 3-3. The flowchart shown in Figure 3-3 depicts the logic necessary to completely erase a PIC18FXX80/XX85 device. The timing diagram that details the "Start Programming" command and parameters P9 and P10 is shown in Figure 3-6.

**Note:** The TBLPTR register must contain the same offset value when initiating the programming sequence as it did when the write buffers were loaded.

TABLE 3-3: ERASE CODE MEMORY CODE SEQUENCE

	2. ERAGE GODE MEMORY GODE GEGERGE		
4-Bit Command	Data Payload	Core Instruction	
Step 1: Direct acco	ess to configuration mer	mory.	
0000	8E A6	BSF EECON1, EEPGD	
0000	8C A6	BSF EECON1, CFGS	
0000	86 A6	BSF EECON1, WREN	
Step 2: Configure	Step 2: Configure device for multi-panel writes.		
0000	0E 3C	MOVLW 3Ch	
0000	6E F8	MOVWF TBLPTRU	
0000	0E 00	MOVLW 00h	
0000	6E F7	MOVWF TBLPTRH	
0000	0E 06	MOVLW 06h	
0000	6E F6	MOVWF TBLPTRL	
1100	00 40	Write 40h to 3C0006h to enable multi-panel erase.	
Step 3: Direct acco	ess to code memory and	d enable erase.	
0000	8E A6	BSF EECON1, EEPGD	
0000	9C A6	BCF EECON1, CFGS	
0000	88 A6	BSF EECON1, FREE	
0000	6A F8	CLRF TBLPTRU	
0000	6A F7	CLRF TBLPTRH	
0000	6A F6	CLRF TBLPTRL	
Step 4: Erase sing	Step 4: Erase single row of all panels at an offset.		
1111	<dummylsb> <dummymsb></dummymsb></dummylsb>	Write 2 dummy bytes and start programming.	
0000	00 00	NOP - hold PGC high for time P9.	
Step 5: Repeat ste	Step 5: Repeat step 4, with Address Pointer incremented by 64 until all panels are erased.		

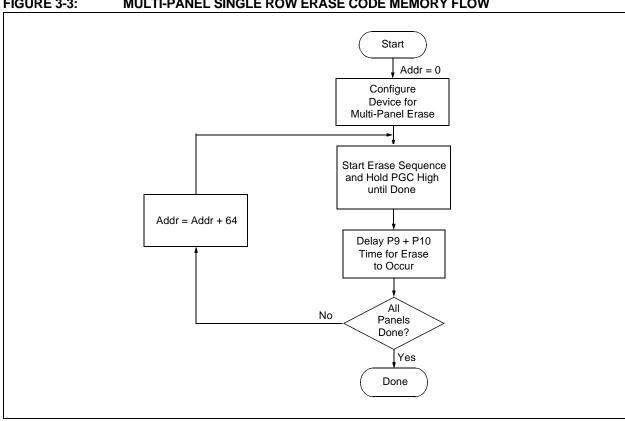


FIGURE 3-3: MULTI-PANEL SINGLE ROW ERASE CODE MEMORY FLOW

#### 3.2 Code Memory Programming

Programming code memory is accomplished by first loading data into the appropriate write buffers and then initiating a programming sequence. Each panel in the code memory space (see Figure 2-4) has an 8-byte deep write buffer that must be loaded prior to initiating a write sequence. The actual memory write sequence takes the contents of these buffers and programs the associated EEPROM code memory.

Typically, all of the program buffers are written in parallel (Multi-Panel Write mode). For example, in the case of a 64-Kbyte device (8 panels with an 8-byte buffer per panel), 64 bytes will be simultaneously programmed during each programming sequence. In this case, the offset of the write within each panel is the same (see Figure 3-4). Multi-Panel Write mode is enabled by appropriately configuring the Programming Control register located at 3C0006h.

The programming duration is externally timed and is controlled by PGC. After a "Start Programming" command is issued (4-bit command, '1111'), a NOP is issued, where the 4th PGC is held high for the duration of the programming time, P9.

After PGC is brought low, the programming sequence is terminated. PGC must be held low for the time specified by parameter P10 to allow high-voltage discharge of the memory array.

The code sequence to program a PIC18FXX80/XX85 device is shown in Table 3-4. The flowchart shown in Figure 3-5 depicts the logic necessary to completely write a PIC18FXX80/XX85 device. The timing diagram that details the "Start Programming" command and parameters P9 and P10 is shown in Figure 3-6.

Note: The TBLPTR register must contain the same offset value when initiating the programming sequence as it did when the write buffers were loaded.

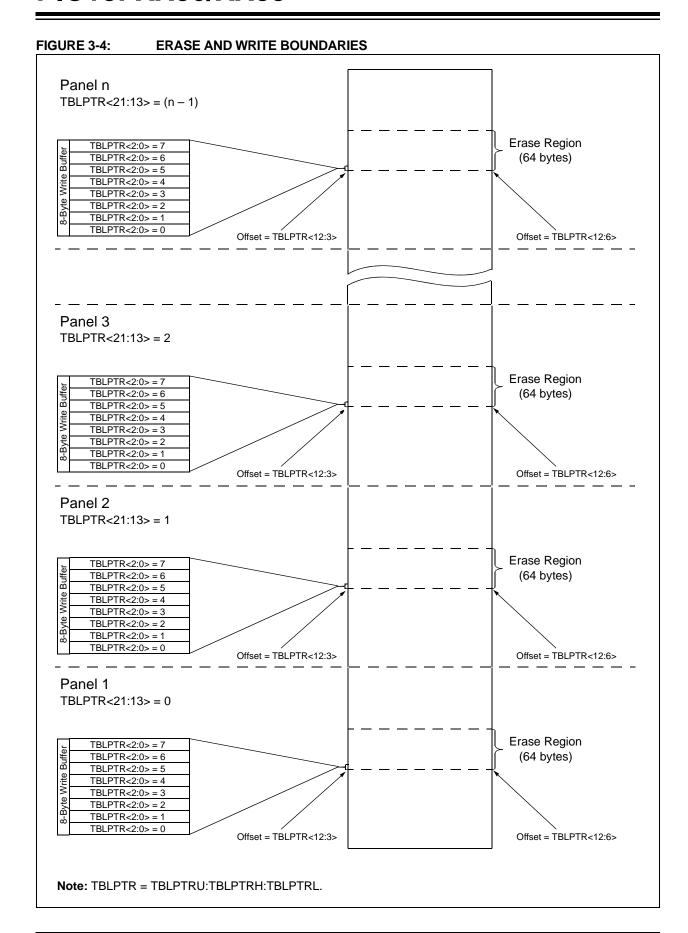
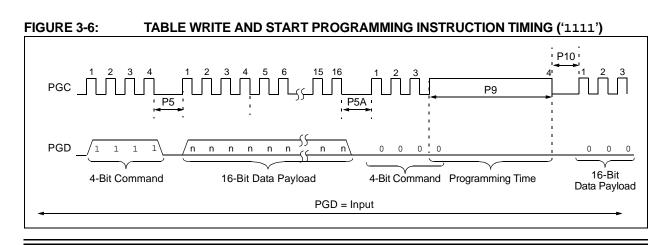


TABLE 3-4: WRITE CODE MEMORY CODE SEQUENCE

4-Bit Command	Data Payload	Core Instruction	
Step 1: Direct acc	Step 1: Direct access to configuration memory.		
0000	8E A6	BSF EECON1, EEPGD	
0000	8C A6	BSF EECON1, CFGS	
0000	86 A6	BSF EECON1, WREN	
Step 2: Configure	device for multi-panel w	vrites.	
0000	0E 3C	MOVLW 3Ch	
0000	6E F8	MOVWF TBLPTRU	
0000	0E 00	MOVLW 00h	
0000	6E F7	MOVWF TBLPTRH	
0000	0E 06	MOVLW 06h	
0000	6E F6	MOVWF TBLPTRL	
1100	00 40	Write 40h to 3C0006h to enable multi-panel writes.	
Step 3: Direct acc	cess to code memory.		
0000	8E A6	BSF EECON1, EEPGD	
0000	9C A6	BCF EECON1, CFGS	
Step 4: Load write	e buffer for Panel 1.		
0000	0E <addr[21:16]></addr[21:16]>	MOVLW <addr[21:16]></addr[21:16]>	
0000	6E F8	MOVWF TBLPTRU	
0000	0E <addr[15:8]></addr[15:8]>	MOVLW <addr[15:8]></addr[15:8]>	
0000	6E F7	MOVWF TBLPTRH	
0000	0E <addr[7:0]></addr[7:0]>	MOVLW <addr[7:0]></addr[7:0]>	
0000	6E F6	MOVWF TBLPTRL	
1101	<lsb><msb></msb></lsb>	Write 2 bytes and post-increment address by 2	
1101	<lsb><msb></msb></lsb>	Write 2 bytes and post-increment address by 2	
1101	<lsb><msb></msb></lsb>	Write 2 bytes and post-increment address by 2	
1100	<lsb><msb></msb></lsb>	Write 2 bytes	
Step 5: Repeat fo			
	r all but the last panel (N	N – 1).	
Step 7: Load write buffer for last panel.			
0000	0E <addr[21:16]></addr[21:16]>		
0000	6E F8	MOVWF TBLPTRU	
0000	0E <addr[15:8]></addr[15:8]>	MOVLW <addr[15:8]></addr[15:8]>	
0000	6E F7	MOVWF TBLPTRH	
0000	0E <addr[7:0]></addr[7:0]>	MOVLW <addr[7:0]></addr[7:0]>	
0000	6E F6	MOVWF TBLPTRL	
1101	<lsb><msb></msb></lsb>	Write 2 bytes and post-increment address by 2	
1101	<lsb><msb></msb></lsb>	Write 2 bytes and post-increment address by 2	
1101	<lsb><msb></msb></lsb>	Write 2 bytes and post-increment address by 2	
1111	<lsb><msb></msb></lsb>	Write 2 bytes and start programming	
0000	00 00	NOP - hold PGC high for time P9	

To continue writing data, repeat steps 2 through 5, where the Address Pointer is incremented by 8 in each panel at each iteration of the loop.

FIGURE 3-5: PROGRAM CODE MEMORY FLOW Start N = 1 LoopCount = 0Configure Device for Multi-Panel Writes Panel Base Address =  $(N - 1) \times 2000h$ Addr = Panel Base Address + (8 x LoopCount) Load 8 Bytes to Panel N Write N = N + 1Buffer at <Addr> All No Panel Buffers Written? Yes N = 1LoopCount = Start Write Sequence and Hold PGC LoopCount + 1 High until Done Delay P9 + P10 Time for Write to Occur All No Locations Done?



Yes Done

#### 3.2.1 SINGLE PANEL PROGRAMMING

The programming example presented in **Section 3.2** "**Code Memory Programming**" utilizes multi-panel programming. This technique greatly decreases the total amount of time necessary to completely program a device and is the recommended method of completely programming a device.

There may be situations, however, where it is advantageous to limit writes to a single panel. In such cases, the user only needs to disable the multi-panel write feature of the device by appropriately configuring the Programming Control register located at 3C0006h.

The single panel that will be written will automatically be enabled based on the value of the Table Pointer.

**Note:** Even though multi-panel writes are disabled, the user must still fill the 8-byte write buffer for the given panel.

#### 3.2.2 MODIFYING CODE MEMORY

All of the programming examples up to this point have assumed that the device has been Bulk Erased prior to programming (see **Section 3.1** "**High-Voltage ICSP Bulk Erase**"). However, it may be the case that the user wishes to modify only a section of an already programmed device.

The minimum amount of data that can be written to the device is 8 bytes. This is accomplished by placing the device in Single Panel Write mode (see Section 3.2.1 "Single Panel Programming"), loading the 8-byte write buffer for the panel and then initiating a write sequence. In this case, it is assumed that the address space to be written already has data in it (i.e., it is not blank).

The minimum amount of code memory that may be erased at a given time is 64 bytes. Again, the device must be placed in Single Panel Write mode. The EECON1 register must then be used to erase the 64-byte target space prior to writing the data.

When using the EECON1 register to act on code memory, the EEPGD bit must be set (EECON1<7> = 1) and the CFGS bit must be cleared (EECON1<6> = 0). The WREN bit must be set (EECON1<2> = 1) to enable writes of any sort (e.g., erases) and this must be done prior to initiating a write sequence. The FREE bit must be set (EECON1<4> = 1) in order to erase the program space being pointed to by the Table Pointer. The erase sequence is initiated by setting the WR bit (EECON1<1> = 1). It is strongly recommended that the WREN bit be set only when absolutely necessary.

To help prevent inadvertent writes when using the EECON1 register, EECON2 is used to "enable" the WR bit. This register must be sequentially loaded with 55h and then AAh, immediately prior to asserting the WR bit in order for the write to occur.

The erase will begin on the falling edge of the 4th PGC after the WR bit is set. After the erase sequence terminates, PGC must still be held low for the time specified by parameter P10 to allow high-voltage discharge of the memory array.

TABLE 3-5: MODIFYING CODE MEMORY

TABLE 3-5:	MODIFYING CODE	WEWORY	
4-Bit Command	Data Payload	Core Instruction	
Step 1: Direct acc	cess to configuration memor	ry.	
0000	8E A6	BSF EECON1, EEPGD	
0000	8C A6	BSF EECON1, CFGS	
Step 2: Configure	device for single panel writ	es.	
0000	0E 3C	MOVLW 3Ch	
0000	6E F8	MOVWF TBLPTRU	
0000	0E 00	MOVLW 00h	
0000	6E F7	MOVWF TBLPTRH	
0000	0E 06	MOVLW 06h	
0000	6E F6	MOVWF TBLPTRL	
1100	00 00	Write 00h to 3C0006h to enable single-panel writes.	
Step 3: Direct acc	cess to code memory.		
0000	8E A6	BSF EECON1, EEPGD	
0000	9C A6	BCF EECON1, CFGS	
Step 4: Set the Ta	able Pointer for the block to	be erased.	
0000	0E <addr[21:16]></addr[21:16]>	MOVLW <addr[21:16]></addr[21:16]>	
0000	6E F8	MOVWF TBLPTRU	
0000	0E <addr[8:15]></addr[8:15]>	MOVLW <addr[8:15]></addr[8:15]>	
0000	6E F7	MOVWF TBLPTRH	
0000	0E <addr[7:0]></addr[7:0]>	MOVLW <addr[7:0]></addr[7:0]>	
0000	6E F6	MOVWF TBLPTRL	
Step 5: Enable m	emory writes and set up an	erase.	
0000	84 A6	BSF EECON1, WREN	
0000	88 A6	BSF EECON1, FREE	
Step 6: Perform re	equired sequence.		
0000	0E 55	MOVLW 55h	
0000	6E A7	MOVWF EECON2	
0000	OE AA	MOVLW OAAh	
0000	6E A7	MOVWF EECON2	
Step 7: Initiate era	ase.		
0000	82 A6	BSF EECON1, WR	
0000	00 00	NOP	
Step 8: Wait for P	Step 8: Wait for P11 + P10 and then disable writes.		
0000	94 A6	BCF EECON1, WREN	
Step 9: Load write	e buffer for panel. The corre	ect panel will be selected based on the Table Pointer.	
0000	0E <addr[8:15]></addr[8:15]>	MOVLW <addr[8:15]></addr[8:15]>	
0000	6E F7	MOVWF TBLPTRH	
0000	0E <addr[7:0]></addr[7:0]>	MOVLW <addr[7:0]></addr[7:0]>	
0000	6E F6	MOVWF TBLPTRL	
1101	<lsb><msb></msb></lsb>	Write 2 bytes and post-increment address by 2	
1101	<lsb><msb></msb></lsb>	Write 2 bytes and post-increment address by 2	
1101	<lsb><msb></msb></lsb>	Write 2 bytes and post-increment address by 2	
1111	<lsb><msb></msb></lsb>	Write 2 bytes and start programming	
0000	00 00	NOP - hold PGC high for time P9	
To continue writin	g data, repeat step 8, where	e the Address Pointer is incremented by 8 at each iteration of the loop.	

### 3.3 Data EEPROM Programming

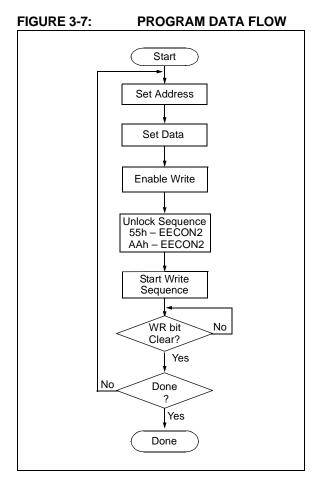
Data EEPROM is accessed one byte at a time via an Address Pointer (register pair, EEADR:EEADRH) and a data latch (EEDATA). Data EEPROM is written by loading EEADR:EEADRH with the desired memory location, EEDATA with the data to be written and initiating a memory write by appropriately configuring the EECON1 and EECON2 registers. A byte write automatically erases the location and writes the new data (erase-before-write).

When using the EECON1 register to perform a data EEPROM write, both the EEPGD and CFGS bits must be cleared (EECON1<7:6> = 00). The WREN bit must be set (EECON1<2> = 1) to enable writes of any sort, and this must be done prior to initiating a write sequence. The write sequence is initiated by setting the WR bit (EECON1<1> = 1). It is strongly recommended that the WREN bit be set only when absolutely necessary.

To help prevent inadvertent writes when using the EECON1 register, EECON2 is used to "enable" the WR bit. This register must be sequentially loaded with 55h and then AAh immediately prior to asserting the WR bit in order for the write to occur.

The write begins on the falling edge of the 4th PGC after the WR bit is set. It ends when the WR bit is cleared by hardware.

After the programming sequence terminates, PGC must still be held low for the time specified by parameter P10 to allow high-voltage discharge of the memory array.





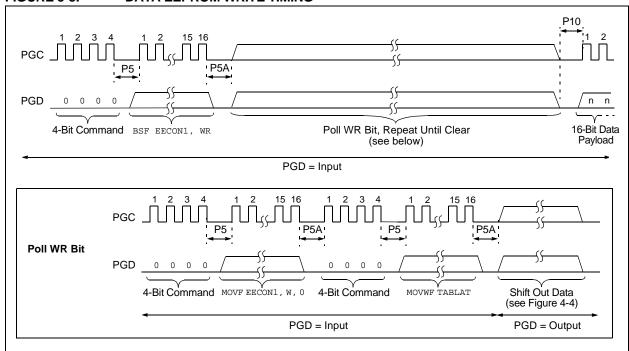


TABLE 3-6: PROGRAMMING DATA MEMORY

4-Bit Command	Data Payload	Core Instruction	
Step 1: Direct acc	Step 1: Direct access to data EEPROM.		
0000	9E A6 9C A6	BCF EECON1, EEPGD BCF EECON1, CFGS	
Step 2: Set the da	ta EEPROM Address Point	er.	
0000 0000 0000 0000	0E <addr> 6E A9 0E <addrh> 6E AA</addrh></addr>	MOVLW <addr> MOVWF EEADR MOVLW <addrh> MOVWF EEADRH</addrh></addr>	
Step 3: Load the	data to be written.		
0000	0E <data> 6E A8</data>	MOVLW <data> MOVWF EEDATA</data>	
Step 4: Enable me	emory writes.		
0000	84 A6	BSF EECON1, WREN	
Step 5: Perform re	equired sequence.		
0000 0000 0000 0000	0E 55 6E A7 0E AA 6E A7	MOVLW 55h MOVWF EECON2 MOVLW 0AAh MOVWF EECON2	
Step 6: Initiate wri	ite.		
0000	82 A6	BSF EECON1, WR	
Step 7: Poll WR b	Step 7: Poll WR bit, repeat until the bit is clear.		
0000 0000 0010	50 A6 6E F5 <lsb><msb></msb></lsb>	MOVF EECON1, W, 0 MOVWF TABLAT Shift out data(1)	
Step 8: Disable w	rites.		
0000	94 A6	BCF EECON1, WREN	
Repeat steps 2 th	Repeat steps 2 through 8 to write more data.		

Note 1: See Figure 4-4 for details on shift out data timing.

### 3.4 ID Location Programming

The ID locations are programmed much like the code memory except that multi-panel writes must be disabled. The single panel that will be written will automatically be enabled based on the value of the Table Pointer. The ID registers are mapped in addresses, 200000h through 200007h. These locations read out normally even after code protection.

**Note:** Even though multi-panel writes are disabled, the user must still fill the 8-byte data buffer for the panel.

Table 3-7 demonstrates the code sequence required to write the ID locations.

TABLE 3-7: WRITE ID SEQUENCE

4-Bit Command	Data Payload	Core Instruction
Step 1: Direct acc	cess to configuration memory	y.
0000 0000	8E A6 8C A6	BSF EECON1, EEPGD BSF EECON1, CFGS
Step 2: Configure	device for single panel write	es.
0000 0000 0000 0000 0000 1100 Step 3: Direct acc	0E 3C 6E F8 0E 00 6E F7 0E 06 6E F6 00 00  cess to code memory.  8E A6 9C A6	MOVLW 3Ch MOVWF TBLPTRU MOVLW 00h MOVWF TBLPTRH MOVLW 06h MOVWF TBLPTRL Write 00h to 3C0006h to enable single panel writes.  BSF EECON1, EEPGD BCF EECON1, CFGS
Step 4: Load write	e buffer. Panel will be autom	atically determined by address.
0000 0000 0000 0000 0000 0000 1101 1101 1111	0E 20 6E F8 0E 00 6E F7 0E 00 6E F6 <lsb><msb> <lsb><msb> <lsb><msb> <lsb><msb> 00 00</msb></lsb></msb></lsb></msb></lsb></msb></lsb>	MOVLW 20h MOVWF TBLPTRU MOVLW 00h MOVWF TBLPTRH MOVLW 00h MOVWF TBLPTRL Write 2 bytes and post-increment address by 2 Write 2 bytes and start programming NOP - hold PGC high for time P9

In order to modify the ID locations, refer to the methodology described in **Section 3.2.2 "Modifying Code Memory"**. As with code memory, the ID locations must be erased before modified.

### 3.5 Boot Block Programming

The Boot Block segment is programmed in exactly the same manner as the ID locations (see **Section 3.4 "ID Location Programming"**). Multi-panel writes must be disabled so that only addresses in the range, 0000h to 07FFh, will be written.

The code sequence detailed in Table 3-7 should be used, except that the address data used in "Step 2" will be in the range, 000000h to 0007FFh.

### 3.6 Configuration Bits Programming

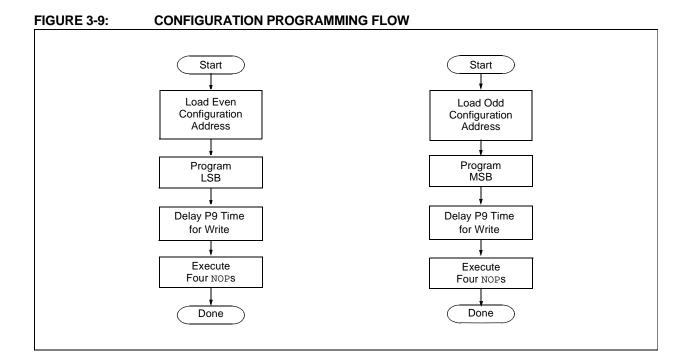
Unlike code memory, the Configuration bits are programmed a byte at a time. The "Table Write, Begin Programming" 4-bit command ('1111') is used, but only 8 bits of the following 16-bit payload will be written. The LSB of the payload will be written to even addresses and the MSB will be written to odd addresses. The code sequence to program two consecutive configuration locations is shown in Table 3-8.

**Note:** Execute four NOPs between every configuration byte programming.

TABLE 3-8: SET ADDRESS POINTER TO CONFIGURATION LOCATION

4-Bit Command	Data Payload	Core Instruction			
Step 1: Direct acc	ess to configuration memory	<i>j.</i>			
0000	8E A6 8C A6	BSF EECON1, EEPGD BSF EECON1, CFGS			
Step 2: Position th	e program counter. <sup>(1)</sup>				
0000	EF 00 F8 00	GOTO 100000h			
Step 3: Set Table	Pointer for configuration byte	e to be written. Write even/odd addresses. <sup>(2)</sup>			
0000 0000 0000 0000 0000 0000 1111 0000 01111	0E 30 6E F8 0E 00 6E F7 0E 00 6E F6 <lsb><msb ignored=""> 00 00 2A F6 <lsb ignored=""><msb> 00 00</msb></lsb></msb></lsb>	MOVLW 30h MOVWF TBLPTRU MOVLW 00h MOVWF TBLPRTH MOVLW 00h MOVWF TBLPTRL Load 2 bytes and start programming NOP - hold PGC high for time P9 INCF TBLPTRL Load 2 bytes and start programming NOP - hold PGC high for time P9			
Step 4: Execute for	Step 4: Execute four NOPs.				
0000 0000 0000 0000	00 00 00 00 00 00 00 00				

- Note 1: If the code protection bits are programmed while the program counter resides in the same block, then the interaction of code protection logic may prevent further table write. To avoid this situation, move the program counter outside the code protection area (e.g., GOTO 100000h).
  - 2: Enabling the write protection of Configuration bits (WRTC = 0 in CONFIG6H) will prevent further writing of Configuration bits. Always write all the Configuration bits before enabling the write protection for Configuration bits.



#### 4.0 READING THE DEVICE

# 4.1 Read Code Memory, ID Locations and Configuration Bits

Code memory is accessed one byte at a time via the 4-bit command, '1001' (table read, post-increment). The contents of memory pointed to by the Table Pointer (TBLPTRU:TBLPTRH:TBLPTRL) are loaded into the table latch and then serially output on PGD.

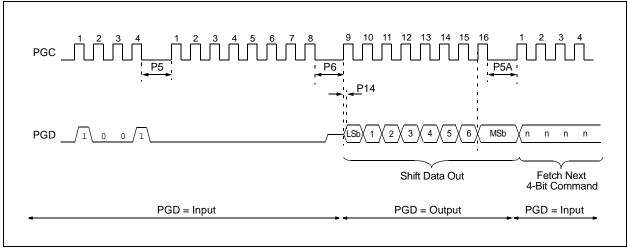
The 4-bit command is shifted in LSb first. The read is executed during the next 8 clocks, then shifted out on PGD during the last 8 clocks, LSb to MSb. A delay of P6 must be introduced after the falling edge of the 8th PGC of the operand to allow PGD to transition from an input to an output. During this time, PGC must be held low (see Figure 4-1). This operation also increments the Table Pointer by one, pointing to the next byte in code memory for the next read.

This technique will work to read any memory in the 000000h to 3FFFFFh address space, so it also applies to the reading of the ID and Configuration registers.

TABLE 4-1: READ CODE MEMORY SEQUENCE

4-Bit Command	Data Payload	Core Instruction			
Step 1: Set Table	Pointer.				
0000 0000 0000 0000 0000	0E <addr[21:16]> 6E F8 0E <addr[15:8]> 6E F7 0E <addr[7:0]> 6E F6</addr[7:0]></addr[15:8]></addr[21:16]>	MOVLW Addr[21:16] MOVWF TBLPTRU MOVLW <addr[15:8]> MOVWF TBLPTRH MOVLW <addr[7:0]> MOVWF TBLPTRL</addr[7:0]></addr[15:8]>			
Step 2: Read men	Step 2: Read memory into table latch and then shift out on PGD, LSb to MSb.				
1001	00 00	TBLRD *+			



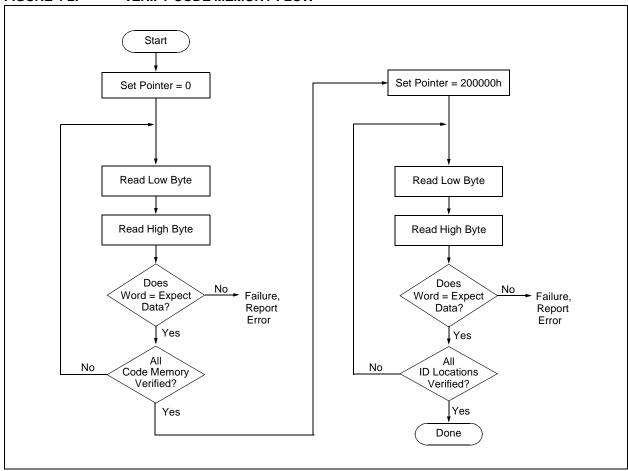


### 4.2 Verify Code Memory and ID Locations

The verify step involves reading back the code memory space and comparing against the copy held in the programmer's buffer. Memory reads occur a single byte at a time, so two bytes must be read to compare against the word in the programmer's buffer. Refer to Section 4.1 "Read Code Memory, ID Locations and Configuration Bits" for implementation details of reading code memory.

The Table Pointer must be manually set to 200000h (base address of the ID locations) once the code memory has been verified. The post-increment feature of the table read 4-bit command may not be used to increment the Table Pointer beyond the code memory space. In a 48-Kbyte device, for example, a post-increment read of address 0BFFFh will wrap the Table Pointer back to 0000h, rather than point to unimplemented address, 0C000h.

FIGURE 4-2: VERIFY CODE MEMORY FLOW



### 4.3 Verify Configuration Bits

A configuration address may be read and output on PGD via the 4-bit command, '1001'. Configuration data is read and written in a byte-wise fashion, so it is not necessary to merge two bytes into a word prior to a compare. The result may then be immediately compared to the appropriate configuration data in the programmer's memory for verification. Refer to Section 4.1 "Read Code Memory, ID Locations and Configuration Bits" for implementation details of reading configuration data.

### 4.4 Read Data EEPROM Memory

Data EEPROM is accessed one byte at a time via an Address Pointer (register pair, EEADR:EEADRH) and a data latch (EEDATA). Data EEPROM is read by loading EEADR:EEADRH with the desired memory location and initiating a memory read by appropriately configuring the EECON1 register. The data will be loaded into EEDATA, where it may be serially output on PGD via the 4-bit command, '0010' (Shift Out Data Holding register). A delay of P6 must be introduced after the falling edge of the 8th PGC of the operand to allow PGD to transition from an input to an output. During this time, PGC must be held low (see Figure 4-4).

The command sequence to read a single byte of data is shown in Table 4-2.

FIGURE 4-3: READ DATA EEPROM FLOW

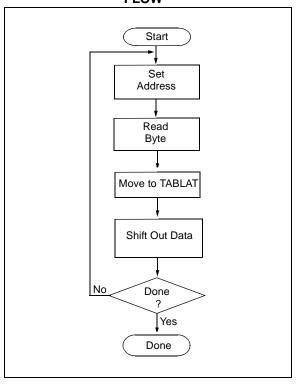
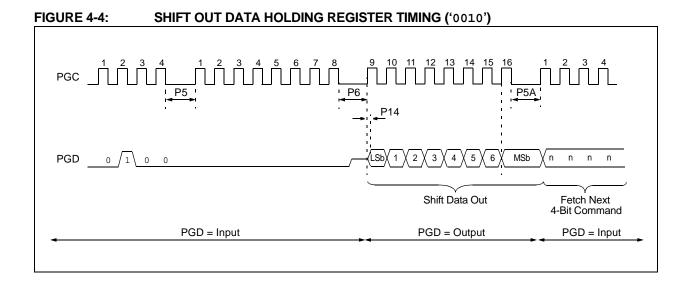


TABLE 4-2: READ DATA EEPROM MEMORY

4-Bit Command	Data Payload	Core Instruction			
Step 1: Direct acc	ess to data EEPROM.				
0000	9E A6 9C A6	BCF EECON1, EEPGD BCF EECON1, CFGS			
Step 2: Set the da	ta EEPROM Address Pointe	er.			
0000 0000 0000 0000	OE <addr> 6E A9 OE <addrh> 6E AA</addrh></addr>	MOVLW <addr> MOVWF EEADR MOVLW <addrh> MOVWF EEADRH</addrh></addr>			
Step 3: Initiate a n	nemory read.				
0000	80 A6	BSF EECON1, RD			
Step 4: Load data	Step 4: Load data into the Serial Data Holding register.				
0000 0000 0010	50 A8 6E F5 <lsb><msb></msb></lsb>	MOVF EEDATA, W, 0 MOVWF TABLAT Shift Out Data(1)			

Note 1: The <LSB> is undefined. The <MSB> is the data.



### 4.5 Verify Data EEPROM

A data EEPROM address may be read via a sequence of core instructions (4-bit command, '0000') and then output on PGD via the 4-bit command, '0010' (Shift Out Data Holding register). The result may then be immediately compared to the appropriate data in the programmer's memory for verification. Refer to **Section 4.4** "**Read Data EEPROM Memory**" for implementation details of reading data EEPROM.

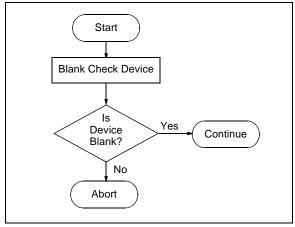
#### 4.6 Blank Check

The term "Blank Check" means to verify that the device has no programmed memory cells. All memories must be verified: code memory, data EEPROM, ID locations and Configuration bits. The Device ID registers (3FFFFEh:3FFFFFh) should be ignored.

A "blank" or "erased" memory cell will read as a '1'. So, "Blank Checking" a device merely means to verify that all bytes read as FFh, except the Configuration bits. Unused (reserved) Configuration bits will read '0' (programmed). Refer to Table 5-2 for blank configuration expect data for the various PIC18FXX80/XX85 devices.

Given that "Blank Checking" is merely code and data EEPROM verification with FFh expect data, refer to Section 4.2 "Verify Code Memory and ID Locations" and Section 4.4 "Read Data EEPROM Memory" for implementation details.

FIGURE 4-5: BLANK CHECK FLOW



#### 5.0 CONFIGURATION WORD

The PIC18FXX80/XX85 devices have several Configuration Words. These bits can be set or cleared to select various device configurations. All other memory areas should be programmed and verified prior to setting Configuration Words. These bits may be read out normally even after read or code-protected.

#### 5.1 ID Locations

A user may store identification information (ID) in eight ID locations, mapped in 200000h:200007h. It is recommended that the Most Significant nibble of each ID be 0Fh. In doing so, if the user code inadvertently tries to execute from the ID space, the ID data will execute as a NOP.

#### 5.2 Device ID Word

The Device ID Word for the PIC18FXX80/XX85 devices is located at 3FFFFEh:3FFFFh. These bits may be used by the programmer to identify what device type is being programmed and read out normally even after code or read-protected.

## 5.3 Low-Voltage Programming (LVP) Bit

The LVP bit in Configuration register, CONFIG4L, enables low-voltage ICSP programming. The LVP bit defaults to a '1' from the factory.

If Low-Voltage Programming mode is not used, the LVP bit can be programmed to a '0' and RB5/PGM becomes a digital I/O pin. However, the LVP bit may only be programmed by entering the High-Voltage ICSP mode, where MCLR/VPP is raised to VIHH. Once the LVP bit is programmed to a '0', only the High-Voltage ICSP mode is available and only the High-Voltage ICSP mode can be used to program the device.

- Note 1: The normal ICSP mode is always available, regardless of the state of the LVP bit, by applying VIHH to the MCLR/VPP pin.
  - **2:** While in Low-Voltage ICSP mode, the RB5 pin can no longer be used as a general purpose I/O.

TABLE 5-1: DEVICE ID VALUES

Device	Device ID Value		
	DEVID2	DEVID1	
PIC18F6585	0Ah	011x xxxx	
PIC18F6680	0Ah	001x xxxx	
PIC18F8585	0Ah	010x xxxx	
PIC18F8680	0Ah	000x xxxx	

TABLE 5-2: PIC18FXX80/XX85 CONFIGURATION BITS AND DEVICE IDS

File	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default/ Unprogrammed Value
300001h	CONFIG1H	-	_	OSCSEN	_	FOSC3	FOSC2	FOSC1	FOSC0	1- 1111
300002h	CONFIG2L	_	_	-		BORV1	BORV0	BODEN	PWRTEN	1111
300003h	CONFIG2H	_	_	_	WDTPS3	WDTPS2	WDTPS1	WDTPS0	WDTEN	1 1111
300004h <sup>(1)</sup>	CONFIG3L	WAIT	_	_	_	_	_	PM1	PM0	111
300005h	CONFIG3H	MCLRE	_	_	_	_	_	ECCPMX <sup>(3)</sup>	CCP2MX	111
300006h	CONFIG4L	DEBUG	_	_			LVP	_	STVREN	11-1
300008h	CONFIG5L	_	_	_	_	CP3 <sup>(2)</sup>	CP2	CP1	CP0	1111
300009h	CONFIG5H	CPD	СРВ	_	_	_	_	_	_	11
30000Ah	CONFIG6L	_	_	_	_	WRT3 <sup>(2)</sup>	WRT2	WRT1	WRT0	1111
30000Bh	CONFIG6H	WRTD	WRTB	WRTC	_	_	_	_	_	111
30000Ch	CONFIG7L	_	_	_	_	EBTR3 <sup>(2)</sup>	EBTR2	EBTR1	EBTR0	1111
30000Dh	CONFIG7H	_	EBTRB	_	_	_	_	_	_	-1
3FFFFEh	DEVID1	DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0	Table 5-1
3FFFFFh	DEVID2	DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3	Table 5-1

**Legend:** - = unimplemented. Shaded cells are unimplemented, read as '0'.

Note 1: Unimplemented in PIC18F6X8X devices; maintain this bit set.

2: Unimplemented in PIC18FX585 devices; maintain this bit set.

3: Reserved in PIC18F6X8X devices; maintain this bit set.

TABLE 5-3: PIC18FXX80/XX85 CONFIGURATION BIT DESCRIPTIONS

Bit Name	Configuration Bytes	Description
OSCEN		Low Power System Clock Option (Timer1) Enable bit 1 = Disabled 0 = Timer1 oscillator system clock option enabled
FOSC3:FOSC0	CONFIG1H	Oscillator Selection bits  1111 = RC oscillator w/OSC2 configured as RA6  1110 = HS oscillator w/software controlled PLL  1101 = EC oscillator with OSC2 configured as RA6 w/SW controlled PLL  1100 = EC oscillator with OSC2 configured as RA6 w/PLL enabled  1011 = Reserved; do not use  1010 = Reserved; do not use  1001 = Reserved; do not use  1000 = Reserved; do not use  1011 = RC oscillator w/OSC2 configured as RA6  0110 = HS oscillator w/OSC2 configured as RA6  0100 = EC oscillator w/OSC2 configured as RA6  0100 = EC oscillator w/OSC2 configured as "divide by 4 clock output"  0011 = RC oscillator  0010 = HS oscillator  0010 = HS oscillator  0010 = LP oscillator
BORV1:BORV0		Brown-out Reset Voltage bits  11 = VBOR set to 2.0V  10 = VBOR set to 2.7V  01 = VBOR set to 4.2V  00 = VBOR set to 4.5V
BOREN	CONFIG2L	Brown-out Reset Enable bit  1 = Brown-out Reset enabled  0 = Brown-out Reset disabled
PWRTEN		Power-up Timer Enable bit 1 = PWRT disabled 0 = PWRT enabled
WDTPS3:WDTPS0	CONFIG2H	Watchdog Timer Postscaler Select bits  1111 = 1:32768  1110 = 1:16384  1101 = 1:8192  1100 = 1:4096  1011 = 1:2048  1010 = 1:1024  1001 = 1:512  1000 = 1:256  0111 = 1:128  0110 = 1:64  0101 = 1:32  0100 = 1:16  0011 = 1:8  0010 = 1:4  0001 = 1:2  0000 = 1:1
WDTEN	-	Watchdog Timer Enable bit  1 = WDT enabled  0 = WDT disabled (control is placed on SWDTEN bit)

Note 1: Unimplemented in PIC18F6X8X (64-pin) devices; maintain this bit set.

- 2: Unimplemented in PIC18FX585 devices; maintain this bit set.
- 3: Reserved for PIC18F6X8X devices; maintain this bit set.

TABLE 5-3: PIC18FXX80/XX85 CONFIGURATION BIT DESCRIPTIONS (CONTINUED)

Bit Name	Configuration Bytes	Description
WAIT <sup>(1)</sup>		External Bus Data Wait Enable bit  1 = Wait selections unavailable  0 = Wait selections determined by WAIT1:WAIT0 bits of MEMCOM register
PM1:PM0 <sup>(1)</sup>	CONFIG3L	Processor Mode Select bits  11 = Microcontroller mode  10 = Microprocessor mode  01 = Microprocessor with Boot Block mode  00 = Extended Microcontroller mode
MCLRE		MCLR Enable bit  1 = MCLR pin enabled, RG5 disabled  0 = MCLR pin disabled, RG5 enabled
ECCPMX		CCP1 PWM Outputs P1B, P1C MUX bit (PIC18F8X8X devices only) <sup>(3)</sup> 1 = P1B, P1C are multiplexed with RE6, RE5 0 = P1B, P1C are multiplexed with RH7, RH6
CCP2MX	CONFIG3H	In Microcontroller mode:  1 = CCP2 input/output is multiplexed with RC1  0 = CCP2 input/output is multiplexed with RE7
		In Microprocessor, Microprocessor with Boot Block and Extended Microcontroller modes (PIC18F8X8X devices only):  1 = CCP2 input/output is multiplexed with RC1  0 = CCP2 input/output is multiplexed with RB3
DEBUG		Background Debugger Enable bit  1 = Background debugger disabled (RB6, RB7 are I/O pins)  0 = Background debugger enabled (RB6, RB7 are ISCP™ pins)
LVP	CONFIG4L	Low-Voltage Programming Enable bit  1 = Low-voltage programming enabled  0 = Low-voltage programming disabled
STVREN		Stack Overflow/Underflow Reset Enable bit  1 = Stack overflow/underflow will cause Reset  0 = Stack overflow/underflow will not cause Reset
CP0		Code Protection bits (code memory area 0800h-3FFFh)  1 = Code memory not code-protected  0 = Code memory code-protected
CP1	CONFICE	Code Protection bits (code memory area 4000h-7FFFh)  1 = Code memory not code-protected  0 = Code memory code-protected
CP2	— CONFIG5L	Code Protection bits (code memory area 8000h-0BFFFh)  1 = Code memory not code-protected  0 = Code memory code-protected
CP3 <sup>(2)</sup>		Code Protection bits (code memory area 0C000h-0FFFh)  1 = Code memory not code-protected  0 = Code memory code-protected
CPD	OONEGEL	Code Protection bits (data EEPROM)  1 = Data EEPROM not code-protected  0 = Data EEPROM code-protected
СРВ	— CONFIG5H	Code Protection bits (boot block, memory area 0000h-07FFh)  1 = Boot block not code-protected  0 = Boot block code-protected

Note 1: Unimplemented in PIC18F6X8X (64-pin) devices; maintain this bit set.

2: Unimplemented in PIC18FX585 devices; maintain this bit set.

3: Reserved for PIC18F6X8X devices; maintain this bit set.

TABLE 5-3: PIC18FXX80/XX85 CONFIGURATION BIT DESCRIPTIONS (CONTINUED)

Bit Name	Configuration Bytes	Description
WRT0		Table Write Protection bit (code memory area 0800h-3FFFh)  1 = Code memory not write-protected  0 = Code memory write-protected
WRT1	CONFIG6L	Table Write Protection bit (code memory area 4000h-7FFFh)  1 = Code memory not write-protected  0 = Code memory write-protected
WRT2	CONFIGUL	Table Write Protection bit (code memory area 8000h-0BFFFh)  1 = Code memory not write-protected  0 = Code memory write-protected
WRT3 <sup>(2)</sup>		Table Write Protection bit (code memory area 0C000h-0FFFFh)  1 = Code memory not write-protected  0 = Code memory write-protected
WRTD		Table Write Protection bit (data EEPROM)  1 = Data EEPROM not write-protected  0 = Data EEPROM write-protected
WRTB	CONFIG6H	Table Write Protection bit (Boot Block, memory area 0000h-07FFh)  1 = Boot block not write-protected  0 = Boot block write-protected
WRTC		Table Write Protection bit (Configuration registers)  1 = Configuration registers not write-protected  0 = Configuration registers write-protected
EBTR0		Table Read Protection bit (code memory area 0800h-3FFFh)  1 = Code memory not protected from table reads executed in other blocks  0 = Code memory protected from table reads executed in other blocks
EBTR1	CONFIG7L	Table Read Protection bit (code memory area 4000h-7FFFh)  1 = Code memory not protected from table reads executed in other blocks  0 = Code memory protected from table reads executed in other blocks
EBTR2	CONFIGIL	Table Read Protection bit (code memory area 8000h-0BFFFh)  1 = Code memory not protected from table reads executed in other blocks  0 = Code memory protected from table reads executed in other blocks
EBTR3 <sup>(2)</sup>		Table Read Protection bit (code memory area 0C000h-0FFFFh)  1 = Code memory not protected from table reads executed in other blocks  0 = Code memory protected from table reads executed in other blocks
EBTRB	CONFIG7H	Table Read Protection bit (Boot Block, memory area 0000h-07FFh)  1 = Boot block not protected from table reads executed in other blocks  0 = Boot block protected from table reads executed in other blocks
DEV10:DEV3	DEVID2	Device ID bits These bits are used with the DEV2:DEV0 bits in the DEVID1 register to identify part number.
DEV2:DEV0	DEVID1	Device ID bits These bits are used with the DEV10:DEV3 bits in the DEVID2 register to identify part number.
REV4:REV0		These bits are used to indicate the revision of the device.

Note 1: Unimplemented in PIC18F6X8X (64-pin) devices; maintain this bit set.

2: Unimplemented in PIC18FX585 devices; maintain this bit set.

3: Reserved for PIC18F6X8X devices; maintain this bit set.

## 5.4 Embedding Configuration Word Information in the HEX File

To allow portability of code, a PIC18FXX80/XX85 programmer is required to read the Configuration Word locations from the HEX file. If Configuration Word information is not present in the HEX file, then a simple warning message should be issued. Similarly, while saving a HEX file, all Configuration Word information must be included. An option to not include the Configuration Word information may be provided. When embedding Configuration Word information in the HEX file, it should start at address 300000h.

Microchip Technology Inc. feels strongly that this feature is important for the benefit of the end customer.

### 5.5 Checksum Computation

The checksum is calculated by summing the following:

- · The contents of all code memory locations
- The Configuration Word, appropriately masked
- · ID locations

The Least Significant 16 bits of this sum are the checksum.

Table 5-4 (pages 32 through 35) describes how to calculate the checksum for each device.

Note:

The checksum calculation differs depending on the code-protect setting. Since the code memory locations read out differently depending on the code-protect setting, the table describes how to manipulate the actual code memory values to simulate the values that would be read from a protected device. When calculating a checksum by reading a device, the entire code memory can simply be read and summed. The Configuration Word and ID locations can always be read.

TABLE 5-4: CHECKSUM COMPUTATION

Device	Code-Protect	Checksum	Blank Value	0AAh at 0 and Max Address
	None	SUM(0000:07FFh) + SUM(0800:3FFFh) + SUM(4000:7FFFh) + SUM(8000:0BFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 00h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 07h) + (CFGW5H & 0C0h) + (CFGW6H & 0E0h) + (CFGW7L & 07h) + (CFGW7H & 40h)	0C357h	0C2ADh
PIC18F6585	Boot Block	SUM(0800:3FFFh) + SUM(4000:7FFFh) + SUM(8000:0BFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 00h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 07h) + (CFGW5H & 80h) + (CFGW6L & 07h) + (CFGW6H & 0E0h) + (CFGW7L & 07h) + (CFGW7H & 40h) + SUM(IDs)	0BB32h	0BAE7h
	Boot/ Block 0/ Block 1	SUM(8000:0BFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 00h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 04h) + (CFGW5H & 80h) + (CFGW6H & 07h) + (CFGW6H & 0E0h) + (CFGW7L & 07h) + (CFGW7H & 40h) + SUM(IDs)	432Fh	42E4h
	All	(CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 00h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 00h) + (CFGW5H & 00h) + (CFGW6H & 0F0h) + (CFGW7L & 07h) + (CFGW7H & 40h) + SUM(IDs)	02A6h	02B5h

Legend: <u>Item</u> <u>Description</u>

CFGW = Configuration Word

SUM[a:b] = Sum of locations, a to b inclusive

SUM\_ID = Byte-wise sum of lower four bits of all customer ID locations

+ = Addition & = Bit-wise AND

TABLE 5-4: CHECKSUM COMPUTATION (CONTINUED)

Device	Code-Protect	Checksum	Blank Value	0AAh at 0 and Max Address
PIC18F6680	None	SUM(0000:07FFh) + SUM(0800:3FFFh) + SUM(4000:7FFFh) + SUM(8000:0BFFFh) + SUM(0C000:0FFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 00h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 0Fh) + (CFGW5H & 0C0h) + (CFGW6L & 0Fh) + (CFGW7L & 0Fh) + (CFGW7H & 40h)	036Fh	02C5h
	Boot Block	SUM(0800:3FFFh) + SUM(4000:7FFFh) + SUM(8000:0BFFFh) + SUM(0C000:0FFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 00h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 0Fh) + (CFGW5H & 80h) + (CFGW6L & 0Fh) + (CFGW6H & 0E0h) + (CFGW7L & 0Fh) + (CFGW7H & 40h) + SUM(IDs)	0FB47h	OFAEDh
	Boot/ Block1/ Block2	SUM(8000:0BFFFh) + SUM(0C000:0FFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 00h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 0Ch) + (CFGW5H & 80h) + (CFGW6L & 0Fh) + (CFGW6H & 0E0h) + (CFGW7L & 0Fh) + (CFGW7H & 40h) + SUM(IDs)	8344h	82EAh
	All	(CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 00h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 00h) + (CFGW5H & 00h) + (CFGW6H & 0E0h) + (CFGW7L & 0Fh) + (CFGW7H & 40h) + SUM(IDs)	02B8h	02B3h

Legend: <u>Item</u> <u>Description</u>

CFGW = Configuration Word

SUM[a:b] = Sum of locations, a to b inclusive

SUM\_ID = Byte-wise sum of lower four bits of all customer ID locations

+ = Addition & = Bit-wise AND

TABLE 5-4: CHECKSUM COMPUTATION (CONTINUED)

Device	Code-Protect	Checksum	Blank Value	0AAh at 0 and Max Address
	None	SUM(0000:07FFh) + SUM(0800:3FFFh) + SUM(4000:7FFFh) + SUM(8000:0BFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 83h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 07h) + (CFGW5H & 0C0h) + (CFGW6H & 0E0h) + (CFGW7L & 0Fh) + (CFGW7H & 40h)	0C3DAh	0C330h
PIC18F8585	Boot Block	SUM(0800:3FFFh) + SUM(4000:7FFFh) + SUM(8000:0BFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 83h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 07h) + (CFGW5H & 80h) + (CFGW6L & 07h) + (CFGW6H & 0E0h) + (CFGW7L & 07h) + (CFGW7H & 40h) + SUM(IDs)	0BBC0h	0BB57h
	Boot/ Block1/ Block2	SUM(8000:0BFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 83h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 04h) + (CFGW5H & 80h) + (CFGW6H & 07h) + (CFGW6H & 0E0h) + (CFGW7L & 07h) + (CFGW7H & 40h) + SUM(IDs)	43BDh	4354h
	All	(CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 83h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 00h) + (CFGW5H & 00h) + (CFGW6H & 0F0h) + (CFGW7L & 07h) + (CFGW7H & 40h) + SUM(IDs)	0339h	0325h

Legend: <u>Item</u> <u>Description</u>

CFGW = Configuration Word

SUM[a:b] = Sum of locations, a to b inclusive

SUM\_ID = Byte-wise sum of lower four bits of all customer ID locations

+ = Addition & = Bit-wise AND

TABLE 5-4: CHECKSUM COMPUTATION (CONTINUED)

Device	Code-Protect	Checksum	Blank Value	0AAh at 0 and Max Address
PIC18F8680	None	SUM(0000:07FFh) + SUM(0800:3FFFh) + SUM(4000:7FFFh) + SUM(8000:0BFFFh) + SUM(0C000:0FFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 83h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 0Fh) + (CFGW5H & 0C0h) + (CFGW6L & 0Fh) + (CFGW6L & 0Fh) + (CFGW7H & 40h)	03F2h	0348h
	Boot Block	SUM(0800:3FFFh) + SUM(4000:7FFFh) + SUM(8000:0BFFFh) + SUM(0C000:0FFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 83h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 0Fh) + (CFGW5H & 80h) + (CFGW6L & 0Fh) + (CFGW6H & 0E0h) + (CFGW7L & 0Fh) + (CFGW7H & 40h) + SUM(IDs)	0FBC6h	0FB6Ch
	Boot/ Block1/ Block2	SUM(8000:0BFFFh) + SUM(0C000:0FFFFh) + (CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 83h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 0Ch) + (CFGW5H & 80h) + (CFGW6L & 0Fh) + (CFGW6H & 0E0h) + (CFGW7L & 0Fh) + (CFGW7H & 40h) + SUM(IDs)	83C3h	8369h
	All	(CFGW1L & 00h) + (CFGW1H & 2Fh) + (CFGW2L & 0Fh) + (CFGW2H & 1Fh) + (CFGW3L & 83h) + (CFGW3H & 80h) + (CFGW4L & 85h) + (CFGW4H & 00h) + (CFGW5L & 00h) + (CFGW5H & 00h) + (CFGW6H & 0E0h) + (CFGW7L & 0Fh) + (CFGW7H & 40h) + SUM(IDs)	0337h	0332h

 Legend:
 Item
 Description

CFGW = Configuration Word

SUM[a:b] = Sum of locations, a to b inclusive

SUM\_ID = Byte-wise sum of lower four bits of all customer ID locations

+ = Addition & = Bit-wise AND

## 5.6 Embedding Data EEPROM Information in the HEX File

To allow portability of code, a PIC18FXX80/XX85 programmer is required to read the data EEPROM information from the HEX file. If data EEPROM information is not present, a simple warning message

should be issued. Similarly, when saving a HEX file, all data EEPROM information must be included. An option to not include the data EEPROM information may be provided. When embedding data EEPROM information in the HEX file, it should start at address F00000h.

Microchip Technology Inc. believes that this feature is important for the benefit of the end customer.

#### AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR 6.0 PROGRAM/VERIFY TEST MODE

**Standard Operating Conditions** 

P1         Tr         MCLR/VPP Rise Time to Enter Program/Verify mode         —         1.0         μs         (Note 1)           P2         Tsclk         Serial Clock (PGC) Period         100         —         ns           P2A         TsclkL         Serial Clock (PGC) Low Time         40         —         ns           P2B         TsclkH         Serial Clock (PGC) High Time         40         —         ns           P3         Tset1         Input Data Setup Time to Serial Clock ↓         15         —         ns           P4         Thld1         Input Data Hold Time from PGC ↓         15         —         ns           P5         Tdly1         Delay Between 4-Bit Command and Command Operand         40         —         ns           P5A         Tdly1a         Delay Between 4-Bit Command Operand and Next 4-Bit Command         40         —         ns           P6         Tdly2         Delay Between Last PGC ↓ of Command Operand and Next 4-Bit Command         40         —         ns           P9         Tdly5         PGC High Time (minimum programming time)         1         —         ms           P10         Tdly6         PGC Low Time After Programming (high-voltage discharge time)         5         —         μs	Operating Temperature: 25°C is recommended							
D110A		Sym	Characteristic	Min	Max	Units	Conditions	
D111	D110	VIHH		9.00	13.25	V		
1.50   5.50   V   Bulk Erase operations	D110A	VIHL		2.00	5.50	V		
D112   IPP	D111	VDD	Supply Voltage During Programming	2.00	5.50	V	Normal programming	
D113         IDDP         Supply Current During Programming         —         10         mA           D031         VIL         Input Low Voltage         Vss         0.2 VDD         V           D041         VIH         Input High Voltage         0.8 VDD         VDD         V           D080         VOL         Output High Voltage         —         0.6         V         IOL = 8.5 mA @ 4.5V           D090         VOH         Output High Voltage         VDD – 0.7         —         V         IOH = -3.0 mA @ 4.5V           D012         Cio         Capacitive Loading on I/O pin (PGD)         —         50         pF         To meet AC specification           P1         Tr         MCLR/VPP Rise Time to Enter Program/Verify mode         —         1.0         µs         (Note 1)           P2         Tsclk         Serial Clock (PGC) Period         100         —         ns           P2A         TsclkL         Serial Clock (PGC) Low Time         40         —         ns           P2B         TsclkH         Serial Clock (PGC) High Time         40         —         ns           P3         Tset1         Input Data Hold Time from PGC ↓         15         —         ns           P5				4.50	5.50	V	Bulk Erase operations	
D031    VIL	D112	IPP	Programming Current on MCLR/VPP	_	300	μΑ		
D041	D113	IDDP	Supply Current During Programming	_	10	mA		
D080	D031	VIL	Input Low Voltage	Vss	0.2 VDD	V		
D090	D041	VIH	Input High Voltage	0.8 VDD	VDD	V		
D012         Cio         Capacitive Loading on I/O pin (PGD)         —         50         pF         To meet AC specification           P1         Tr         MCLR/VPP Rise Time to Enter Program/Verify mode         —         1.0         μs         (Note 1)           P2         Tsclk         Serial Clock (PGC) Period         100         —         ns           P2A         TsclkL         Serial Clock (PGC) Low Time         40         —         ns           P2B         TsclkH         Serial Clock (PGC) High Time         40         —         ns           P3         Tset1         Input Data Setup Time to Serial Clock ↓         15         —         ns           P4         ThId1         Input Data Hold Time from PGC ↓         15         —         ns           P5         Tdly1         Delay Between 4-Bit Command and Command Operand         40         —         ns           P5A         Tdly1a         Delay Between Last PGC ↓ of Command Operand and Next 4-Bit Command         —         ns           P6         Tdly2         Delay Between Last PGC ↓ of Read of Data Word         —         ns           P9         Tdly5         PGC High Time (minimum programming time)         1         —         ms           P10         Tdly6 <td>D080</td> <td>Vol</td> <td>Output Low Voltage</td> <td>_</td> <td>0.6</td> <td>V</td> <td>IOL = 8.5 mA @ 4.5V</td>	D080	Vol	Output Low Voltage	_	0.6	V	IOL = 8.5 mA @ 4.5V	
P1 Tr   MCLR/VPP Rise Time to Enter   Program/Verify mode   Mote 1)   MS   (Note 1)	D090	Voн	Output High Voltage	VDD - 0.7	_	V	IOH = -3.0 mA @ 4.5V	
P2         Tsclk         Serial Clock (PGC) Period         100         —         ns           P2A         TsclkL         Serial Clock (PGC) Low Time         40         —         ns           P2B         TsclkH         Serial Clock (PGC) High Time         40         —         ns           P3         Tset1         Input Data Setup Time to Serial Clock ↓         15         —         ns           P4         Thld1         Input Data Hold Time from PGC ↓         15         —         ns           P5         Tdly1         Delay Between 4-Bit Command and Command Operand         40         —         ns           P5A         Tdly1a         Delay Between 4-Bit Command Operand and Next 4-Bit Command Operand Input Word         20         —         ns           P6         Tdly2         Delay Between Last PGC ↓ of Read of Data Word         20         —         ns           P9         Tdly5         PGC High Time (minimum programming time)         1         —         ms           P10         Tdly6         PGC Low Time After Programming (high-voltage discharge time)         5         —         µs           P11         Tdly7         Delay t	D012	Сю	Capacitive Loading on I/O pin (PGD)	_	50	pF	To meet AC specifications	
P2         Tsclk         Serial Clock (PGC) Period         100         —         ns           P2A         TsclkL         Serial Clock (PGC) Low Time         40         —         ns           P2B         TsclkH         Serial Clock (PGC) High Time         40         —         ns           P3         Tset1         Input Data Setup Time to Serial Clock ↓         15         —         ns           P4         Thld1         Input Data Hold Time from PGC ↓         15         —         ns           P5         Tdly1         Delay Between 4-Bit Command and Command Operand         40         —         ns           P5A         Tdly1a         Delay Between 4-Bit Command Operand and Next 4-Bit Command Operand Input Word         20         —         ns           P6         Tdly2         Delay Between Last PGC ↓ of Read of Data Word         20         —         ns           P9         Tdly5         PGC High Time (minimum programming time)         1         —         ms           P10         Tdly6         PGC Low Time After Programming (high-voltage discharge time)         5         —         µs           P11         Tdly7         Delay t								
P2A         TsclkL         Serial Clock (PGC) Low Time         40         —         ns           P2B         TsclkH         Serial Clock (PGC) High Time         40         —         ns           P3         Tset1         Input Data Setup Time to Serial Clock ↓         15         —         ns           P4         Thld1         Input Data Hold Time from PGC ↓         15         —         ns           P5         Tdly1         Delay Between 4-Bit Command and Command Operand         40         —         ns           P5A         Tdly1a         Delay Between 4-Bit Command Operand and Next 4-Bit Command         40         —         ns           P6         Tdly2         Delay Between Last PGC ↓ of Command Byte to First PGC ↑ of Read of Data Word         20         —         ns           P9         Tdly5         PGC High Time (minimum programming time)         1         —         ms           P10         Tdly6         PGC Low Time After Programming (high-voltage discharge time)         5         —         μs           P11         Tdly7         Delay to Allow Self-Timed Data Write or Bulk Erase to Occur         10         —         ms           P11A         Tdrwt         Data Write Polling Time         4         —         ms           <	P1	Tr		_	1.0	μS	(Note 1)	
P2B TsclkH Serial Clock (PGC) High Time 40 — ns P3 Tset1 Input Data Setup Time to Serial Clock ↓ 15 — ns P4 ThId1 Input Data Hold Time from PGC ↓ 15 — ns P5 Tdly1 Delay Between 4-Bit Command and Command Operand 40 — ns P5A Tdly1a Delay Between 4-Bit Command 40 — ns P6A Tdly2 Delay Between Last PGC ↓ of Command Byte to First PGC ↑ of Read of Data Word P7 Tdly5 PGC High Time (minimum programming time) P10 Tdly6 PGC Low Time After Programming (high-voltage discharge time) P11 Tdly7 Delay to Allow Self-Timed Data Write or Bulk Erase to Occur P11A Tdrwt Data Write Polling Time 4 — ms P12 ThId2 Input Data Hold Time from MCLR/VPP ↑ 2 — μs	P2	Tsclk	Serial Clock (PGC) Period	100	_	ns		
P3       Tset1       Input Data Setup Time to Serial Clock ↓       15       —       ns         P4       Thld1       Input Data Hold Time from PGC ↓       15       —       ns         P5       Tdly1       Delay Between 4-Bit Command and Command Operand       40       —       ns         P5A       Tdly1a       Delay Between 4-Bit Command Operand and Next 4-Bit Command       40       —       ns         P6       Tdly2       Delay Between Last PGC ↓ of Command Byte to First PGC ↑ of Read of Data Word       20       —       ns         P9       Tdly5       PGC High Time (minimum programming time)       1       —       ms         P10       Tdly6       PGC Low Time After Programming (high-voltage discharge time)       5       —       μs         P11       Tdly7       Delay to Allow Self-Timed Data Write or Bulk Erase to Occur       10       —       ms         P11A       Tdrwt       Data Write Polling Time       4       —       ms         P12       Thld2       Input Data Hold Time from MCLR/VPP ↑       2       —       μs	P2A	TsclkL	Serial Clock (PGC) Low Time	40	_	ns		
P4       ThId1       Input Data Hold Time from PGC ↓       15       —       ns         P5       Tdly1       Delay Between 4-Bit Command and Command Operand       40       —       ns         P5A       Tdly1a       Delay Between 4-Bit Command       40       —       ns         P6       Tdly2       Delay Between Last PGC ↓ of Command Byte to First PGC ↑ of Read of Data Word       20       —       ns         P9       Tdly5       PGC High Time (minimum programming time)       1       —       ms         P10       Tdly6       PGC Low Time After Programming (high-voltage discharge time)       5       —       μs         P11       Tdly7       Delay to Allow Self-Timed Data Write or Bulk Erase to Occur       10       —       ms         P11A       Tdrwt       Data Write Polling Time       4       —       ms         P12       ThId2       Input Data Hold Time from MCLR/VPP ↑       2       —       μs	P2B	TsclkH	Serial Clock (PGC) High Time	40	_	ns		
P5       Tdly1       Delay Between 4-Bit Command Command Operand       40       —       ns         P5A       Tdly1a       Delay Between 4-Bit Command Operand and Next 4-Bit Command       40       —       ns         P6       Tdly2       Delay Between Last PGC ↓ of Command Byte to First PGC ↑ of Read of Data Word       20       —       ns         P9       Tdly5       PGC High Time (minimum programming time)       1       —       ms         P10       Tdly6       PGC Low Time After Programming (high-voltage discharge time)       5       —       μs         P11       Tdly7       Delay to Allow Self-Timed Data Write or Bulk Erase to Occur       10       —       ms         P11A       Tdrwt       Data Write Polling Time       4       —       ms         P12       Thld2       Input Data Hold Time from MCLR/VPP ↑       2       —       μs	P3	Tset1	Input Data Setup Time to Serial Clock ↓	15	_	ns		
Command Operand         P5A       Tdly1a       Delay Between 4-Bit Command Operand and Next 4-Bit Command       40       —       ns         P6       Tdly2       Delay Between Last PGC ↓ of Command Byte to First PGC ↑ of Read of Data Word       20       —       ns         P9       Tdly5       PGC High Time (minimum programming time)       1       —       ms         P10       Tdly6       PGC Low Time After Programming (high-voltage discharge time)       5       —       μs         P11       Tdly7       Delay to Allow Self-Timed Data Write or Bulk Erase to Occur       10       —       ms         P11A       Tdrwt       Data Write Polling Time       4       —       ms         P12       Thld2       Input Data Hold Time from MCLR/VPP ↑       2       —       μs	P4	Thld1	Input Data Hold Time from PGC ↓	15	_	ns		
Operand and Next 4-Bit Command         P6       Tdly2       Delay Between Last PGC ↓ of Command Byte to First PGC ↑ of Read of Data Word       20       —       ns         P9       Tdly5       PGC High Time (minimum programming time)       1       —       ms         P10       Tdly6       PGC Low Time After Programming (high-voltage discharge time)       5       —       μs         P11       Tdly7       Delay to Allow Self-Timed Data Write or Bulk Erase to Occur       10       —       ms         P11A       Tdrwt       Data Write Polling Time       4       —       ms         P12       Thld2       Input Data Hold Time from MCLR/VPP ↑       2       —       μs	P5	Tdly1		40	_	ns		
Command Byte to First PGC ↑ of Read of Data Word  P9 Tdly5 PGC High Time (minimum programming time)  P10 Tdly6 PGC Low Time After Programming (high-voltage discharge time)  P11 Tdly7 Delay to Allow Self-Timed Data Write or Bulk Erase to Occur  P11A Tdrwt Data Write Polling Time 4 — ms  P12 Thld2 Input Data Hold Time from MCLR/VPP ↑ 2 — μs	P5A	Tdly1a		40	_	ns		
(minimum programming time)         P10       Tdly6       PGC Low Time After Programming (high-voltage discharge time)       5       —       μs         P11       Tdly7       Delay to Allow Self-Timed Data Write or Bulk Erase to Occur       10       —       ms         P11A       Tdrwt       Data Write Polling Time       4       —       ms         P12       Thld2       Input Data Hold Time from MCLR/VPP ↑       2       —       μs	P6	Tdly2	Command Byte to First PGC ↑ of Read	20	_	ns		
(high-voltage discharge time)         P11       Tdly7       Delay to Allow Self-Timed Data Write or Bulk Erase to Occur       10       —       ms         P11A       Tdrwt       Data Write Polling Time       4       —       ms         P12       Thld2       Input Data Hold Time from MCLR/VPP↑       2       —       μs	P9	Tdly5		1	_	ms		
Bulk Erase to Occur   P11A   Tdrwt   Data Write Polling Time   4   —   ms	P10	Tdly6		5		μS		
P12 ThId2 Input Data Hold Time from MCLR/VPP↑ 2 — μs	P11	Tdly7		10		ms		
	P11A	Tdrwt	Data Write Polling Time	4	_	ms		
	P12	Thld2	Input Data Hold Time from MCLR/VPP ↑	2	_	μS		
P13 Tset2 VDD ↑ Setup Time to MCLR/VPP ↑ 100 — ns	P13	Tset2	VDD ↑ Setup Time to MCLR/VPP ↑	100	_	ns		
P14 Tvalid Data Out Valid from PGC ↑ 10 — ns	P14	Tvalid	Data Out Valid from PGC ↑	10	_	ns		
P15 Tset3 PGM↑Setup Time to MCLR/VPP↑ 2 — μs	P15	Tset3	PGM ↑ Setup Time to MCLR/VPP ↑	2	_	μS		

Note 1: Do not allow excess time when transitioning MCLR between VIL and VIHH; this can cause spurious program executions to occur. The maximum transition time is:

where TCY is the instruction cycle time, TPWRT is the Power-up Timer period and ToSC is the oscillator period. For specific values, refer to the Electrical Characteristics section of the device data sheet for the particular device.

<sup>1</sup> TCY + TPWRT (if enabled) + 1024 TOSC (for LP, HS, HS/PLL and XT modes only)

<sup>+ 2</sup> ms (for HS/PLL mode only) + 1.5  $\mu$ s (for EC mode only)

#### Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the
  intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our
  knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
  Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

#### **Trademarks**

The Microchip name and logo, the Microchip logo, dsPIC, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, rfPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Octopus, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, PIC<sup>32</sup> logo, REAL ICE, rfLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2010, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

QUALITY MANAGEMENT SYSTEM

CERTIFIED BY DNV

ISO/TS 16949:2002

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



### WORLDWIDE SALES AND SERVICE

#### **AMERICAS**

**Corporate Office** 

2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://support.microchip.com

Web Address: www.microchip.com

Atlanta

Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

**Boston** 

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca. IL

Tel: 630-285-0071 Fax: 630-285-0075

Cleveland

Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Kokomo

Kokomo, IN Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara

Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto

Mississauga, Ontario,

Canada

Tel: 905-673-0699 Fax: 905-673-6509 ASIA/PACIFIC
Asia Pacific Office

Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon

Hong Kong Tel: 852-2401-1200

Fax: 852-2401-3431

Australia - Sydney

Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8528-2100 Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Hong Kong SAR

Tel: 852-2401-1200 Fax: 852-2401-3431

China - Nanjing

Tel: 86-25-8473-2460 Fax: 86-25-8473-2470

China - Qingdao

Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Xiamen

Tel: 86-592-2388138 Fax: 86-592-2388130

**China - Zhuhai** Tel: 86-756-3210040

Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Yokohama

Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Daegu

Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-6578-300 Fax: 886-3-6578-370

Taiwan - Kaohsiung Tel: 886-7-536-4818

Fax: 886-7-536-4803

Taiwan - Taipei

Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351 Fax: 66-2-694-1350 EUROPE

Austria - Wels

Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

**Germany - Munich** 

Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan

Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen

Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid

Tel: 34-91-708-08-90 Fax: 34-91-708-08-91 **UK - Wokingham** 

Tel: 44-118-921-5869 Fax: 44-118-921-5820

01/05/10